

ABSTRACT OF THE DISCLOSURE

A surface of an external electrode 3 of an electronic part 4 is formed with a coating containing resin ingredient. Thereby, adhesion strength and reliability may be significantly improved in mounting an electronic part onto a circuit board 1 through the medium of a conductive adhesive. Further, it will be able to mount an electronic part to an element to be mounted by utilizing a conductive adhesive forming an external electrode 3 as a connecting element.

Further, surface roughness (R_a) of an external electrode 3 of an electronic part is set to $0.1\ \mu\text{m}$ or more and to $10.0\ \mu\text{m}$ or less and preferably to $1.0\ \mu\text{m}$ or more and to $5.0\ \mu\text{m}$ or less. Thereby, adhesion strength with a conductive adhesive may be significantly enhanced in comparison with a conventional electronic part presented.